Application No.: 10/530,516

Attorney Docket No.: 02886.0092-00000

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently Amended) A pretreatment method for an electroless plating material, comprising:

irradiating a resin material with ultraviolent rays while said resin material is in contact with a first solution consisting of, said first solution containing ozone in an organic or inorganic polar solvent other than water,

wherein the organic polar solvent is selected from the group consisting of methanol, isopropyl alcohol, N,N-dimethylformaldehyde, N,N-dimethylacetamide, dimethyl sulfoxide, N-methyl-pyrrolidon, hexamethylphosphoramide, formic acid, acetic acid, and mixtures thereof,

wherein the inorganic polar solvent is selected from the group consisting of nitric acid, hydrochloric acid, hydrorfluoric acid, and

wherein the resin material irradiated by the ultraviolet rays while in contact with the first solution lacks a surface having prior roughening.

2. (Previously Presented) A pretreatment method for an electroless plating material as claimed in claim 1, further comprising bringing said resin material, after said ozone solution-ultraviolet irradiation step, into contact with a second solution containing an alkaline component.

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3. (Original) A pretreatment method for an electroless plating material as claimed in claim 2, wherein said second solution further contains at least one of an anionic surface active agent and a nonionic surface active agent.

4. (Canceled)

- 5. (Currently Amended) A method for producing a member having a plated coating, comprising:
- (a) irradiating a resin material with ultraviolet rays while said resin material is in contact with a first solution containing consisting of ozone in an organic or inorganic polar solvent other than water, and
 - (b) electroless plating said resin material,

wherein the organic polar solvent is selected from the group consisting of methanol, isopropyl alcohol, N,N-dimethylformaldehyde, N,N-dimethylacetamide, dimethyl sulfoxide, N-methyl-pyrrolidon, hexamethylphosphoramide, formic acid, acetic acid, and mixtures thereof,

wherein the inorganic polar solvent is selected from the group consisting of nitric acid, hydrochloric acid, hydrorfluoric acid, and

wherein the resin material irradiated by the ultraviolet rays while in contact with the first solution lacks a surface having prior roughening.

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6. (Previously Presented) A method for producing a member having a plated coating as claimed in claim 5, further comprising bringing said resin material into contact with a second solution containing an alkaline component, between said ozone solution-ultraviolet irradiation treating process and said electroless plating process.

7. (Original) A method for producing a member having a plated coating as claimed in claim 6, wherein said second solution further contains at least one of an anionic surface active agent and a nonionic surface active agent.

8. (Canceled)

- 9. (Previously Presented) A method for producing a member having a plated coating as claimed in claim 5, further comprising subjecting said resin material, after said electroless plating step, to electroplating.
- 10. (Previously Presented) A pretreatment method for an electroless plating material as claimed in claim 1, wherein the organic polar solvent is selected from the group consisting of N,N-dimethylformaldehyde, N,N-dimethylacetamide, dimethyl sulfoxide, N-methyl-pyrrolidon, hexamethylphosphoramide, formic acid, acetic acid, and mixtures thereof.
- 11. (Previously Presented) A method for producing a member having a plated coating as claimed in claim 5, wherein the organic polar solvent is selected from the

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group consisting of N,N-dimethylformaldehyde, N,N-dimethylacetamide, dimethyl sulfoxide, N-methyl-pyrrolidon, hexamethylphosphoramide, formic acid, acetic acid, and mixtures thereof.